

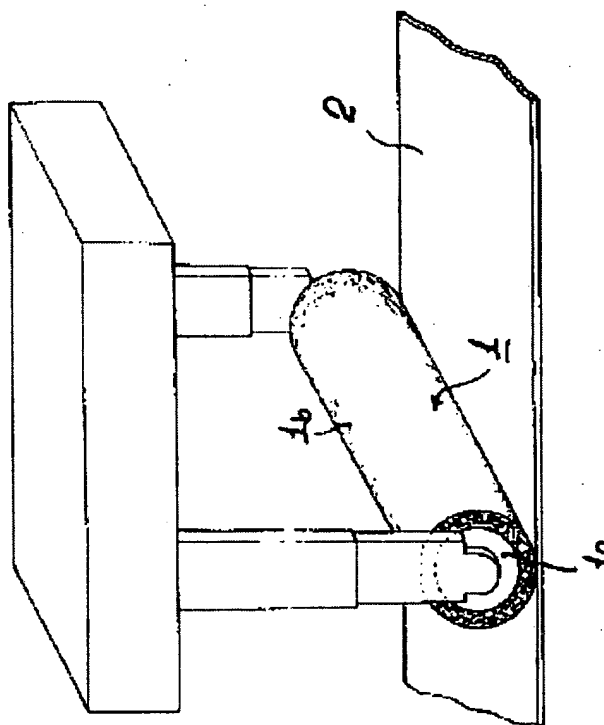
PLATING METHOD

Patent number: JP57171690
Publication date: 1982-10-22
Inventor: OOSAKI TOKIO; others: 01
Applicant: TOKIO OOSAKI; others: 02
Classification:
- **International:** C25D5/06
- **European:**
Application number: JP19810056132 19810413
Priority number(s):

Abstract of JP57171690

PURPOSE: To easily perform desired plating to the surface of a substance to be treated, by pressing the surface of the substance to be treated, by use of a roller to which a plating liquid and electrically conducted, and also turning and moving it.

CONSTITUTION: Plating is performed by feeding power to a roller 1 consisted of a roller core 1a consisting of a metal, carbon, etc., and a solution impregnating material 1b wound round its outside circumference to necessary thickness, to which a plating liquid has been fed, turning this roller 1, pressing the surface of a substance to be treated 2, and moving the roller 1. The impregnating material 1b of said roller 1 is impregnated with a plating liquid obtained by ionizing a desired metal. Also, to the roller 1 side and the substance to be treated 2 side, the positive pole side of a DC power supply and the negative pole side are connected respectively, and plating is performed in electrically-conducting. As a result, desired plating can be performed easily to the surface of the substance to be treated, by only making the roller contact with the substance to be treated, and a plating liquid tank is not required, therefore, the quantity of the plating liquid can be saved.



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